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#### General Information

|                          |                                           |
|--------------------------|-------------------------------------------|
| Series                   | SMD Comm X8G HT150C Flex                  |
| Style                    | SMD Chip                                  |
| Description              | SMD, MLCC, High Temperature, Ultra-Stable |
| Features                 | High Temperature, Ultra-Stable            |
| RoHS                     | Yes                                       |
| Termination              | Flexible Termination                      |
| Marking                  | No                                        |
| AEC-Q200                 | No                                        |
| Typical Component Weight | 4.6 mg                                    |
| Shelf Life               | 78 Weeks                                  |
| MSL                      | 1                                         |

#### Specifications

|                                                                    |                                                 |
|--------------------------------------------------------------------|-------------------------------------------------|
| Capacitance                                                        | 1,500 pF                                        |
| Measurement Condition                                              | 1 kHz 1.0Vrms                                   |
| Tolerance                                                          | 10%                                             |
| Voltage DC                                                         | 200 VDC                                         |
| Dielectric Withstanding Voltage                                    | 500 VDC                                         |
| Temperature Range                                                  | -55/+150°C                                      |
| Temp. Coefficient                                                  | X8G                                             |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms                          |
| Dissipation Factor                                                 | 0.1% 1 kHz 1.0Vrms                              |
| Aging Rate                                                         | 0% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance                                              | 100 GOhms                                       |

#### Dimensions

|           |                  |
|-----------|------------------|
| Chip Size | 0603             |
| L         | 1.6mm +/-0.17mm  |
| W         | 0.8mm +/-0.15mm  |
| T         | 0.85mm +/-0.07mm |
| S         | 0.4mm MIN        |
| B         | 0.45mm +/-0.15mm |

#### Packaging Specifications

|                    |                        |
|--------------------|------------------------|
| Packaging          | T&R, 330mm, Paper Tape |
| Packaging Quantity | 10000                  |

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